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FOR IMMEDIATE RELEASE

Press Release

SMT 256EP New High Viscous Solder Joint Encapsulant Adhesive Paste

(Albany, NY) 06/01/2017 — YINCAE has developed a new innovative solder joint encapsulant paste. Designed to be used for mass production via dispensing or printing, SMT 256EP replaces traditional solder paste, flux, and underfill.

SMT 256EP enhances solder joint strength by 5 to 10 times and has demonstrated high pull strength at both room and high temperatures (280°C). At 280°C, SMT 256EP has a pull strength up to 180g. Thus, SMT 256EP eliminates the RTV or red glue that is typically used to hold components during double reflow, and reduces manufacturing costs.

This product is commercially available and used by companies for package level applications. SMT 256EP is an innovative product that demonstrates outstanding thermocycling performance, cost efficiency, and the ability to be reflowed at 230°C, used for high temperature applications (300°C). These results point to SMT 256EP being the next generation adhesive for the Microelectronics industry.

For more information on YINCAE's SMT 256EP, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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